ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	PC, Bannockl	burn, Illinois. A	Il rights reserved nations.	under both	This docume level parts, t	ent is a declara he declaration	tion of the sencompass	substances es all lowe	within the m er level mater	anufacture	er listed iter nich the mar	n. Note: nufacture	if the item is an as r has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distril				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					us Materia	ials and Mfg Information				
Supplier Information															
Company name*			Company unique ID			Unique ID Authority					Response Date*				
onsemi											2024-05-18				
Contact Name Title - Contact				Phone - Contact*						Email - Contact*					
Product-Env-Stewards Product Enviro C			ro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Represent			entative !			Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Da	e Versior	n :	Manufacturing Site		W	eight*	UOM	Unit Type	
	NRVTS: G	IRVTS5100ETFSTW 5A 100V Trench S		Schottky u8FL		2024-05-18			MY1		32	.25	mg	Each	
Aanufacturing Proccess Informa	tion														
Terminal Plating / Grid Array Ma	y Material Terminal Base Alloy		Alloy	J-STD-020 MS	L Rating	Peak Pro	Process Body Temperature Max Time at Peak		e at Peak	Temperature Number of Reflow Cycles		cles			
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		seconds	3				
omments															
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select	the Level (IIG A IIG B	Requester or Supplier) [B	l select the subst	ance category (JIG or Requester) or enter	a value (Supplier) [C] selec	t the substance (II	G) or enter the substa	nce and CAS (Other) [D
select a RoHS exemption, if applic	cable [E] enter the weigh	t of the substance or the Pl	PM concentration	[F] Optionally enter the positive (+) and	negative (-) tolerance in per	cent (Note: percer	it tolerance values are	expected to cover a 3
sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	2.98	mg	Supplier	Zinc (Zn)	7440-66-6		0.0036	mg
			Supplier	Iron (Fe)	7439-89-6		0.07	mg
			Supplier	Copper (Cu)	7440-50-8		2.9055	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0009	mg
Die	0.47	mg	Supplier	Silicon (Si)	7440-21-3		0.47	mg
Die Attach Solder	0.79	mg	Supplier	Silver (Ag)	7440-22-4		0.0198	mg
			А	Lead (Pb)	7439-92-1	7a	0.7308	mg
			Supplier	Tin (Sn)	7440-31-5		0.0395	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.1353	mg
			Supplier	Iron (Fe)	7439-89-6		0.0174	mg
			Supplier	Copper (Cu)	7440-50-8		12.2536	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg